

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Canceled)
2. (Canceled)
3. (Canceled)
4. (Canceled)
5. (Canceled)
6. (Canceled)
7. (Canceled)
8. (Canceled)
9. (Canceled)
10. (New) A resin composition, capable of being employed for forming a resin layer of a resin-attached metal foil, comprising:
 - a cyanate resin and/or a prepolymer thereof;
 - an epoxy resin substantially containing no halogen atom;
 - a phenoxy resin substantially containing no halogen atom;
 - an imidazole compound; and
 - an inorganic filler.
11. (New) A resin composition, capable of being employed for forming an insulating sheet of a base material-attached insulating sheet, comprising:
 - a cyanate resin and/or a prepolymer thereof;
 - an epoxy resin substantially containing no halogen atom;
 - a phenoxy resin substantially containing no halogen atom;
 - an imidazole compound; and
 - an inorganic filler.
12. (New) The resin composition according to claim 10, wherein said cyanate resin is a novolac cyanate resin.

13. (New) The resin composition according to claim 11, wherein said cyanate resin is a novolac cyanate resin.
14. (New) The resin composition according to claim 10, wherein said epoxy resin is an aryl alkylene epoxy resin.
15. (New) The resin composition according to claim 11, wherein said epoxy resin is an aryl alkylene epoxy resin.
16. (New) The resin composition according to claim 10, wherein said imidazole compound has two or more functional groups selected from a group consisting of aliphatic hydrocarbon group, aromatic hydrocarbon group, hydroxyalkyl group and cyano alkyl group.
17. (New) The resin composition according to claim 11, wherein said imidazole compound has two or more functional groups selected from a group consisting of aliphatic hydrocarbon group, aromatic hydrocarbon group, hydroxyalkyl group and cyano alkyl group.
18. (New) A resin-attached metal foil, formed by cladding a metal foil with the resin composition according to claim 10.
19. (New) A multiple-layered printed wiring board, formed by laying the resin-attached metal foil(s) according to claim 18 on a single side or both sides of an internal layer circuit board and hot pressure forming thereof.
20. (New) A base material-attached insulating sheet, formed by cladding an insulating base material with the resin composition according to claim 11.
21. A multiple-layered printed wiring board, formed by laying the base material-attached insulating sheet(s) according to claim 20 on a single side or both sides of an internal layer circuit board and hot pressure forming thereof.